



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-10-24
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS40SM120CT	RTDZ*ZA6M02Z	A	SHENZHEN B/E	2016-10-24
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10-9.1-4.5	3	THROUGH HOLE	
Comment	TO 220 AB NON ISOL			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
5 - Product(s) is obsolete, no information is available	FALSE
6 - Product(s) is unknown, no information is available	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RTD2*ZAGM02Z					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	15.815	mg	supplier	die	Silicon (Si)	7440-21-3		14.875	mg	940563	7829
				supplier	metallization	Aluminium (Al)	7429-90-5		0.616	mg	38950	324
				supplier	metallization	Titanium (Ti)	7440-32-6		0.014	mg	886	7
				supplier	metallization	Tungsten (W)	7440-33-7		0.022	mg	1391	12
				supplier	metallization	Nickel (Ni)	7440-02-0		0.067	mg	4236	35
				supplier	Passivation	Silicon Oxide	7631-86-9		0.091	mg	5754	48
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	443	4
				supplier	back side metallization	Gold (Au)	7440-57-5		0.022	mg	1391	12
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.101	mg	6386	53
				Leadframe	Copper & its alloys	1259.453	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						1.253	mg	995	659
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.376	mg	299	198
supplier	metallization	Nickel (Ni)	7440-02-0						6.408	mg	5088	3373
supplier	metallization	Phosphorus (P)	12185-10-3						0.040	mg	31	22
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Soft solder	Solder	13.800	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	13.179	mg	955000	6936
				supplier	solder	Silver (Ag)	7440-22-4		0.345	mg	25000	182
				supplier	solder	Tin (Sn)	7440-31-5		0.276	mg	20000	145
Bonding Ribbons	Other Nonferrous metals & alloys	4.850	mg	supplier	Ribbon	Aluminium (Al)	7429-90-5		4.850	mg	1000000	2553
Encapsulation	Other Organic Materials	599.720	mg	supplier	mold compound	Silica, vitreous	60676-86-0		521.756	mg	869999	274608
				supplier	mold compound	Epoxy resin	25068-38-6		59.972	mg	100000	31564
				supplier	mold compound	Phenol resin	29690-82-2		14.993	mg	25000	7891
				supplier	mold compound	Carbon Black	1333-86-4		2.999	mg	5001	1578
Connections coating	Solder	6.362	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.362	mg	1000000	3348